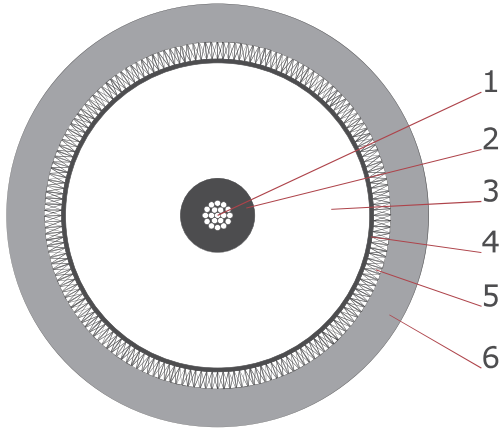


HSL-30-0.38-SS-C-0

30kV_{DC} / 9kV_{AC} - AWG22 - SILICONE DIELECTRIC

CONSTRUCTION



1. Conductor	AWG22 Cu/Ag (19xAWG34 s.p.c.)	0.38mm ² Ø 0.75mm
2. Semicon	Semiconductive Silicone	Ø 1.95mm
3. Dielectric	Silicone	Ø 8.0mm ± 0.25mm
4. Semicon	Semiconductive Tape	Ø 8.2mm
5. Braid	Cu/Sn (0.15mm t.p.c.) ≥85% Coverage	Ø 9.1mm ± 0.3mm
6. Jacket	Silicone	Ø 11.1mm ± 0.3mm

TECHNICAL DATA

Rated Voltage	30kV _{DC} /9kV _{AC}
Test Voltage	80kV _{DC} / 1min (conductor / braid) 25kV _{AC} (Spark Test, core) 2.5kV _{AC} (Spark Test, jacket)
Conductor Resistance @ 20°C	≤ 52.17Ω/km
Impedance	typ. 45Ω
Capacitance	typ. 140pF/m
min. Bend Radius	111mm (moving), 84mm (fixed)
Operating Temperature	-50°C - +180°C
RoHS Compliant	Yes
Weight	ca. 0.155kg/m
Cu-Weight	ca. 0.047kg/m
Color	black
Status	Y (Preliminary)

